REMARKS

At the outset, Applicant thanks the Examiner for examining the pending application. The Office Action dated August 20, 2008 has been received and its contents carefully reviewed.

Applicant has amended claims 1, 2 and 27 to further define the invention and deleted claims 10 and 28. No new matter has been added. Thus, claims 1-9 and 11-27 are currently pending with claims 11-26 having been withdrawn from consideration. Applicant respectfully requests reconsideration of pending claims.

The Office Action rejects claims 1-9 and 27-28 under 35 U.S.C. 103(a) as being unpatentable over Applicant's Admitted Related Art (hereinafter "ARA"). Applicant respectfully traverses the rejections.

Claim 1, as amended, is allowable over the cited references in that claim 1 recites a combination of elements including, for example, "…a first conductive layer and a pad layer on the substrate; a first insulating layer on the first conductive layer and the pad layer, the first insulating layer having a contact hole exposing a portion of the pad layer; a semiconductor layer on the first insulating layer; a second conductive layers on the semiconductor layer; a third conductive layers on the second conductive layers; a second insulating layer on the third conductive layers, the second insulating layer having a first contact hole exposing a portion of the third conductive layers, and a second contact hole exposing the portion of the pad layer exposed by the first insulating layer; a fourth conductive layer on the second insulating layer and electrically contacting a portion of the third conductive layers; a fifth conductive layer on the second insulating layer and electrically contacting the pad layer through the second contact hole; and a sixth conductive layers on the exposed portion of the third conductive layers and on the exposed portion of the pad layer, the sixth conductive layer contacting the third conductive layer and the pad layer; wherein the sixth conductive layers are only formed in the first contact hole and in the contact hole of the first insulating layer, and wherein the first conductive layer and the pad layer are a single layer"(Emphasis Added). None of the cited references, singly or in combination, teaches or suggests at least this feature of the claim 1. See Figs. 1A-1E and paragraphs [0008]-[0009] of "ARA". In particular, lines 8-15 of the paragraph [0009] show that a gate line, a gate electrode 12 and a gate pad 14 are a double layer structure such as Mo/AlNd,

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Mo/Al or Cr/AlNd. Thus, "ARA" fails to teach at least "wherein the first conductive layer and the pad layer are a single layer". For at least this reason, Applicant submits that claim 1 and claims 2-9 and 27, which depend therefrom, are allowable over the cited references.
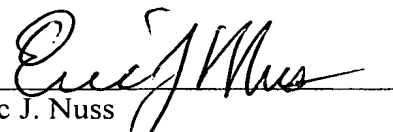
The application is in condition for allowance and early, favorable action is respectfully solicited.

If for any reason the Examiner finds the application other than in condition for allowance, the Examiner is requested to call the undersigned attorney at (202) 496-7500 to discuss the steps necessary for placing the application in condition for allowance. All correspondence should continue to be sent to the below-listed address.

If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 C.F.R. §1.136, and any additional fees required under 37 C.F.R. §1.136 for any necessary extension of time, or any other fees required to complete the filing of this response, may be charged to Deposit Account No. 50-0911. Please credit any overpayment to deposit Account No. 50-0911.

Dated: November 20, 2008

Respectfully submitted,

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